

Technology Landscape, Trends and Opportunities in the Global HDI PCB Market

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Abstracts

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The technologies in HDI PCB market have undergone significant change in recent years, traditional low density technology advance high density PCBs. The rising wave of new technologies, such as 10+ layer technology are creating significant potential in smartphone, tablets, and automotive applications, and driving the demand for HDI PCB technologies.

In HDI PCB market, various technologies, such as 4-6 layers, 8-10 layers, and 10+ layers are used in various applications. Growth in consumer electronics, miniaturization of electronic devices, increasing demand for high performance PCBs, and growing adoption of advanced electronics and safety measures in the automotive are creating new opportunities for various HDI PCB technologies.

This report analyzes technology maturity, degree of disruption, competitive intensity, market potential, and other parameters of various technologies in the HDI PCB market. Some insights are depicted below by a sample figure. For more details on figures, the companies researched, and other objectives/benefits on this research report, please download the report brochure.

The study includes technology readiness, competitive intensity, regulatory compliance, disruption potential, trends, forecasts and strategic implications for the global HDI PCB technology by application, technology, and region as follows:

Technology Readiness by Technology Type

Competitive Intensity and Regulatory Compliance

Disruption Potential by Technology Type

Trends and Forecasts by Technology Type [\$M shipment analysis for 2018 t%li%2030]:

4-6 Layer

8-10 Layer

10+ Layer

Trends and Forecasts by Application [\$M shipment analysis for 2018 t%li%2030]:

Smartphone and Tablets

4-6 Layer

8-10 Layer

10+ Layer

Telecom/Datacom

4-6 Layer

8-10 Layer

10+ Layer

Computer

4-6 Layer

8-10 Layer

10+ Layer

Consumer Electronics

4-6 Layer

8-10 Layer

10+ Layer

Automotive

4-6 Layer

8-10 Layer

10+ Layer

Trends and Forecasts by Region [\$M shipment analysis for 2018 t%li%2030]:

North America

United States

Canada

Mexico

Europe

United Kingdom

Germany

France

Asia Pacific

Japan

China

South Korea

India

The Rest of the World

Latest Developments and Innovations HDI PCB Technologies

Companies / Ecosystems

Strategic Opportunities by Technology Type

Some of the companies profiled in this report include Siemens AG, Compeq Manufacturing Co. Ltd., TTM Technologies, Inc., Unimicron, AT&S, Ibiden Group, SEMCO, Unitech Printed Circuit Board Corp., Tripod Technology Corp., DAP Corporation, and Meik%li%Electronics Co. Ltd

This report answers following 9 key questions:

Q.1 What are some of the most promising and high-growth technology opportunities for the HDI PCB market?

Q.2 Which technology will grow at a faster pace and why?

Q.3 What are the key factors affecting dynamics of different technologies? What are the drivers and challenges of these technologies in HDI PCB market?

Q.4 What are the levels of technology readiness, competitive intensity and regulatory compliance in this technology space?

Q.5 What are the business risks and threats t%li%these technologies in HDI PCB market?

Q.6 What are the latest developments in HDI PCB technologies? Which companies are leading these developments?

Q.7 Which technologies have potential of disruption in this market?

Q.8 Who are the major players in this HDI PCB market? What strategic initiatives are being implemented by key players for business growth?

Q.9 What are strategic growth opportunities in this HDI PCB technology space?

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- 9.9. Tripod Technology Corp.
- 9.10. DAP Corporation
- 9.11. Meiko Electronics Co. Ltd

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